ACT® CMI-S
ORGANIC ETCH RESIDUE AND POSITIVE PHOTORESIST STRIPPER

ACT CMI-S is a corrosion inhibited water-soluble solution which effectively removes hard-processed positive resist and organic etch residue from corrosion-sensitive metal alloy substrates.

BENEFITS
- Low etch rates on aluminum and aluminum alloys
- Completely water-soluble
- Operating temperature of 60°C to 75°C
- Compatible with wet bench and spray tool processes

TYPICAL PHYSICAL PROPERTIES
- Specific Gravity: 0.940
- Boiling Point: 164°C
- Freezing Point: <-15°C
- Flash Point (Open cup): 78°C
- Flash Point (Closed cup): 63°C
- Viscosity @25°C: 1.12 cSt
- pH (5% solution): 10.26

MATERIAL COMPATIBILITY
ACT CMI-S is compatible with the following materials used in the semiconductor industry*:

- Chemraz® 570
- Halar 901
- Kalrez® 6375
- PFA
- POE Polyethylene, Cross Linked
- Polyethylene, High Density
- Polyethylene, UHMW
- Polypropylene
- Stainless Steel 316L
- Stainless Steel 316LEP
- Teflon® PTFE

INSTRUCTIONS FOR USE

ACT CMI-S
60°C - 75°C
5 to 30 minutes
either
or
DI Water
ambient
5 minutes
Dry

ACT CMI-S
ambient
5 minutes
**ACT® CMI-S**

**ETCH RATES**

<table>
<thead>
<tr>
<th>Temp.</th>
<th>Al</th>
<th>Cu</th>
<th>Ti</th>
<th>Ta</th>
<th>TaN</th>
<th>W</th>
<th>TiN</th>
<th>TiW</th>
</tr>
</thead>
<tbody>
<tr>
<td>75°C</td>
<td>1</td>
<td>18</td>
<td>&lt;1</td>
<td>&lt;1</td>
<td>&lt;1</td>
<td>3</td>
<td>&lt;1</td>
<td>1</td>
</tr>
</tbody>
</table>

**Etch Rates (Å/min)**

**Thickness measurements were performed using a CDE ResMap 273 four-point probe for metal films and the Nanospec® AFT model 010-0180 film thickness measurement system for oxide films.**

**STORAGE, HANDLING, AND PROTECTIVE CLOTHING**

Contact the Air Products Technical Center at 1-800-752-1597 or gastech@airproducts.com for a MSDS.
tell me more
www.airproducts.com/electronics